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Part Number:

0737800253

Status:

Active

Overview:

HDM Backplane Connector System

Description:

HDM Board-to-Board Daughtercard Receptacle, Vertical, Signal Module, 72 Circuits, Mounted Height 13.00mm, Pin Length 3.50mm, Solder Tail

Documents:

3D Model

Test Summary TS-73670-990-001 (PDF)

Drawing (PDF)

RoHS Certificate of Compliance (PDF)

Product Specification PS-73780-999-001 (PDF)

Agency Certification

UL

E29179

General

Product Family

Backplane Connectors

Series

73780

Application

Daughtercard, Mezzanine

Comments

Solder Tail, Solder Tail

Component Type

PCB Receptacle

Overview

HDM Backplane Connector System

Product Name

HDM

UPC

756054405895

Physical

Circuits (Loaded)

72

Circuits (maximum)

72

Color - Resin

Black

Durability (mating cycles max)

250

First Mate / Last Break

No

Flammability

94V-0

Guide to Mating Part

No

Keying to Mating Part

None

Material - Metal

Copper-Nickel-Tin

Material - Plating Mating

Gold

Material - Plating Termination

Tin

Material - Resin

High Temperature Thermoplastic

Net Weight

10.002/g

Number of Columns

12

Number of Pairs

Open Pin Field

Number of Rows

6

Orientation

Vertical

PC Tail Length

3.50mm

PCB Locator

No

PCB Retention

None

PCB Thickness - Recommended

1.60mm

Packaging Type

Tube

Pitch - Mating Interface

2.00mm

Pitch - Termination Interface

2.00mm

Plating min - Mating

0.762µm

Plating min - Termination

2.540µm

Polarized to PCB

No

Stackable

Yes

Surface Mount Compatible (SMC)

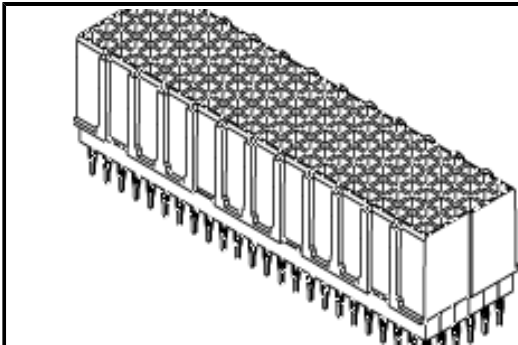
Yes

Temperature Range - Operating

-55° to +105°C

Termination Interface: Style

Through Hole



Series image - Reference only

EU ELV

Not Relevant

EU RoHS

China RoHS

Compliant

REACH SVHC

Not Contained Per -

ED/71/2019 (16 July

2019)

Halogen-Free

Status

Low-Halogen

For more information, please visit [Contact US](#)

China ROHS

Green Image

ELV

Not Relevant

RoHS Phthalates

Not Contained

Search Parts in this Series

73780 Series

Mates With

HDM Board-to-Board Backplane Header

73642 , 73643 , 73644 , 73942 , 73943 ,

73944 , 7 4349, 74428. HDM Board-to-

Board Stacking Header 73769 , 73770 ,

73782 , 73783 , 73771

Electrical

Current - Maximum per Contact	15.0A, 1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	005
Lead-freeProcess Capability	WAVE
Max. Cycles at Max. Process Temperature	001
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Product Specification	PS-73780-999-001
Sales Drawing	SD-73780-004
Test Summary	TS-73670-990-001

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